

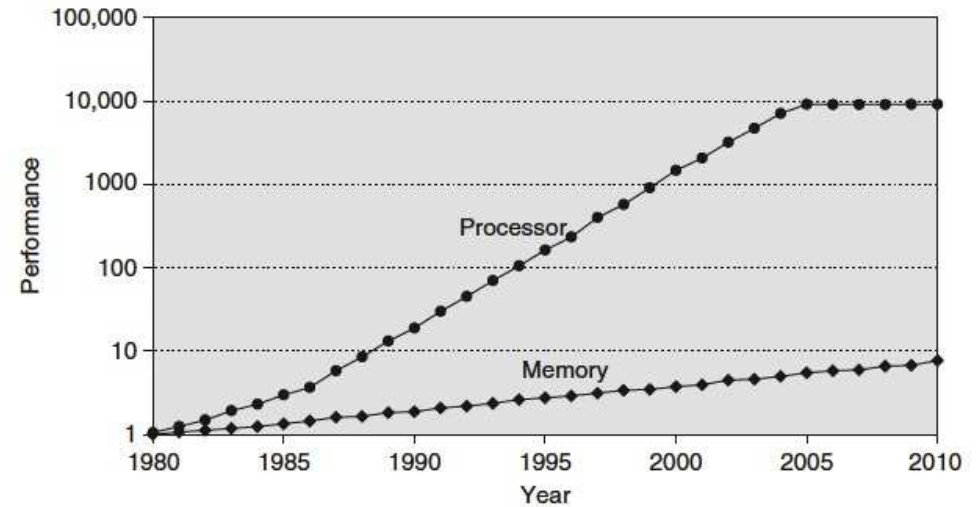
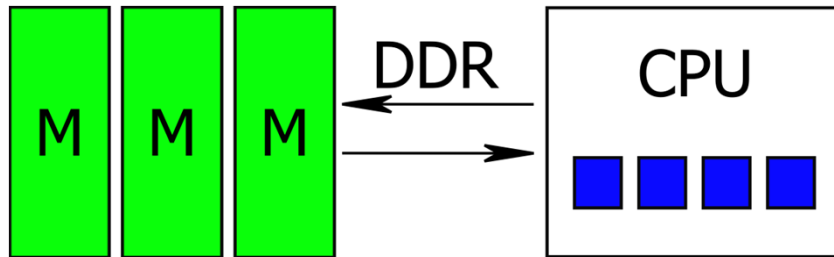


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Emerging memory technologies for improved energy efficiency

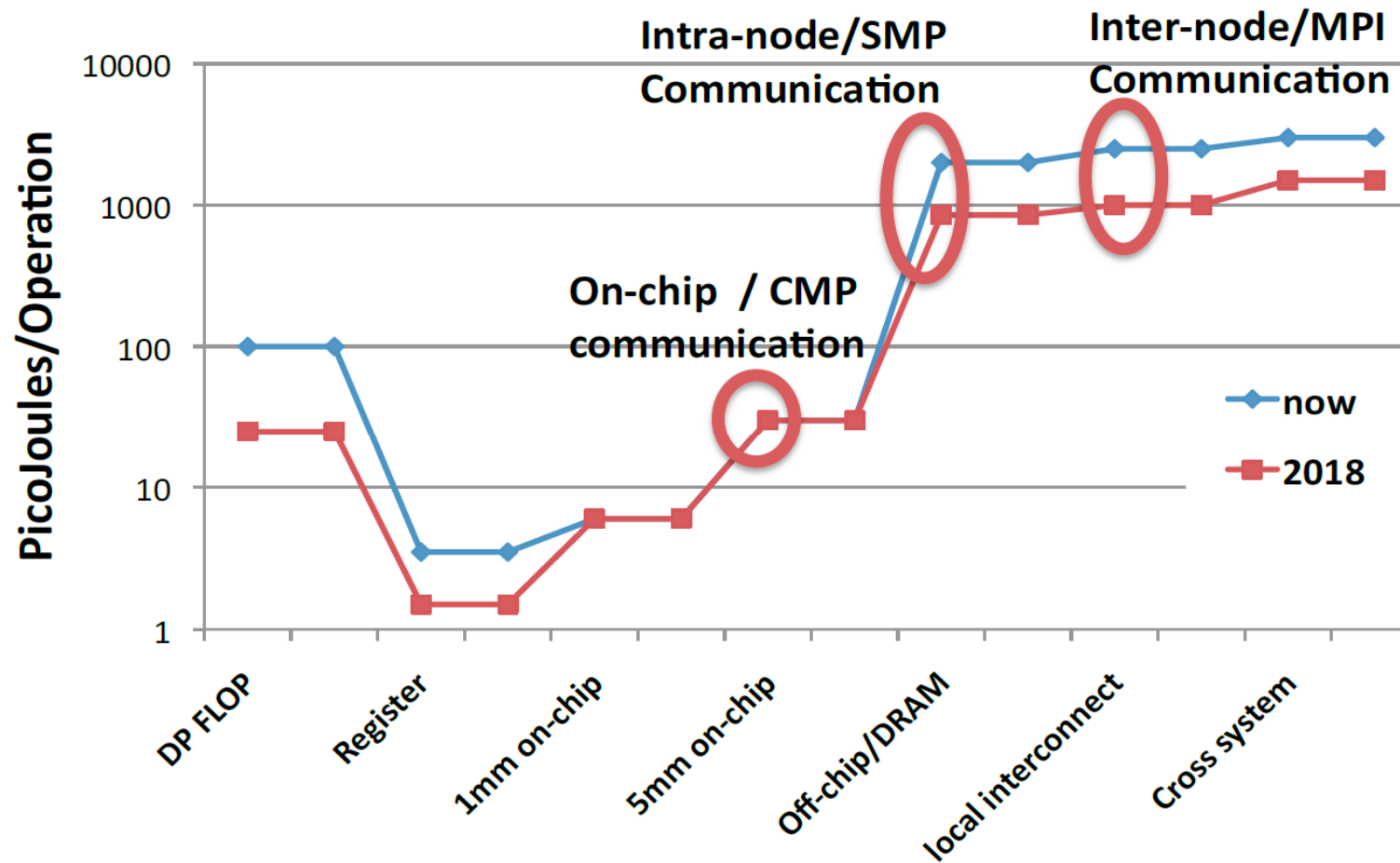
Martin Wenzel
Advanced Seminar
WS2015

Memory Bandwidth

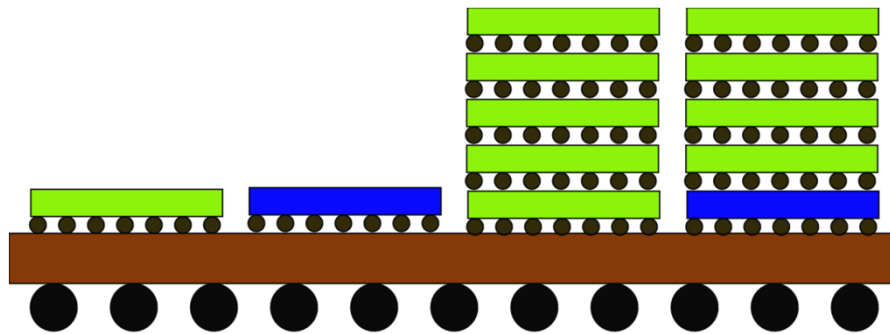


Technology	BW GB/s
DDR3-1333 2GB	10,66
DDR4-2667 4GB	21,34

Power Consumption



Stacking

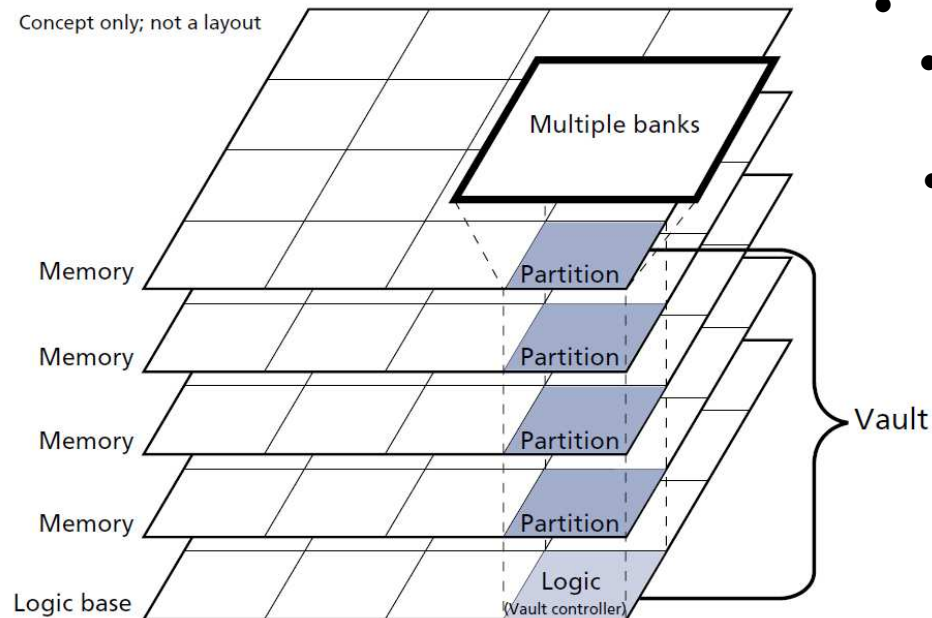


- Pricy
- Thermal Resistance
- High Density
- Low Interconnect Length
- High Internal Interconnect Width

- $\sim 400 \frac{\mu\text{Bumps}}{\text{mm}^2}$

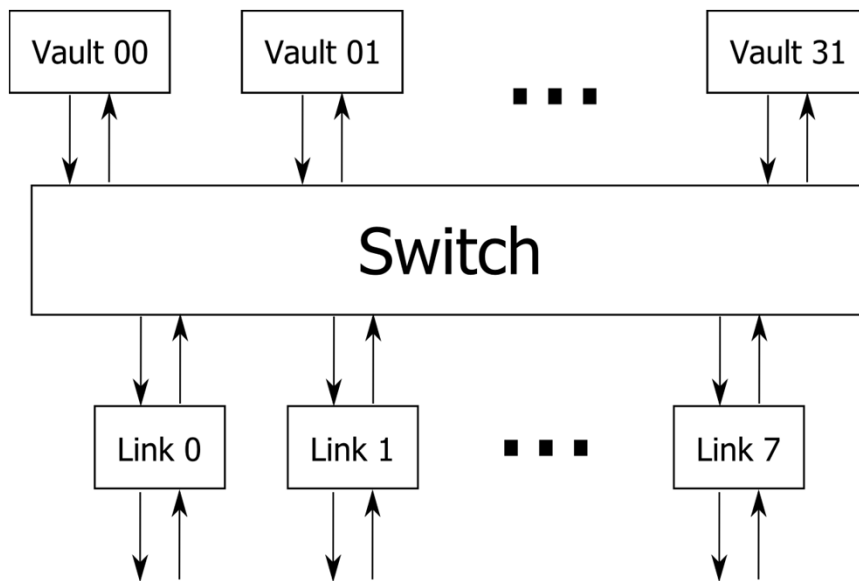
- Package limited $< 4 \frac{\text{Bumps}}{\text{mm}^2}$

Stacked Memory Hybrid Memory Cube

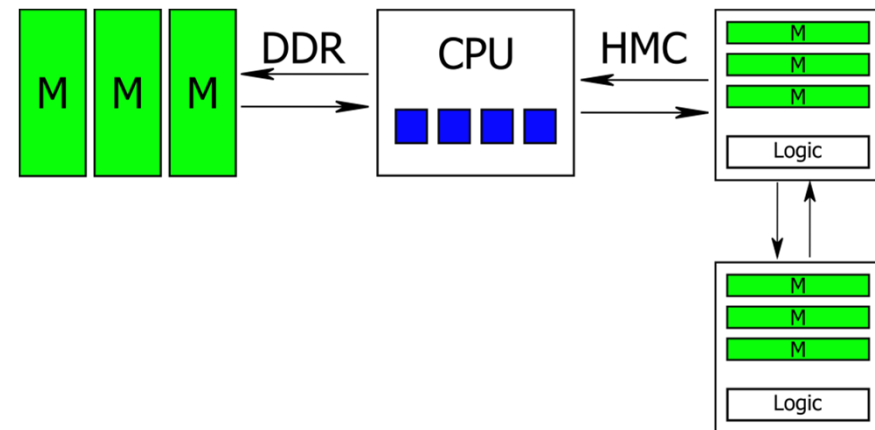


- 32 Vaults
 - Vertical Memory partitions
- Vault Logic
 - DRAM Controller
 - Packetized Interconnect
 - Support for Atomics
 - Arithmetic
 - Bitwise swap / write
 - Boolean
 - Compare and Swap

Hybrid Memory Cube Interconnect



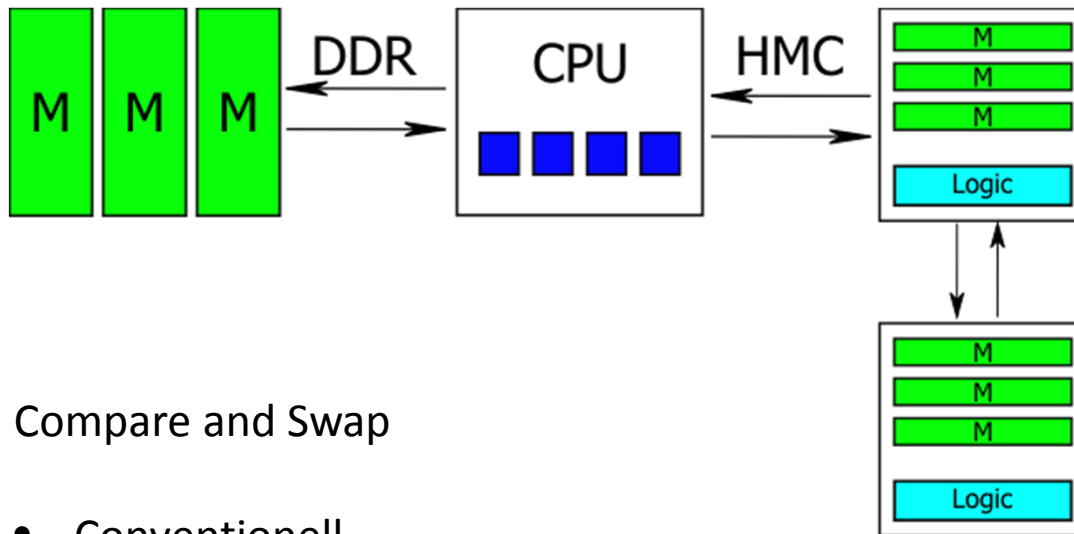
- Packet based Interconnect
- 20GB/s Per Link
- 8 Links per HMC
 - Aggregate Link Bandwidth
 - Connect additional HMCs



Technology	BW GB/s
DDR3-1333 2GB	10,66
DDR4-2667 4GB	21,34



Processing in Memory (PIM) Instruction Offloading



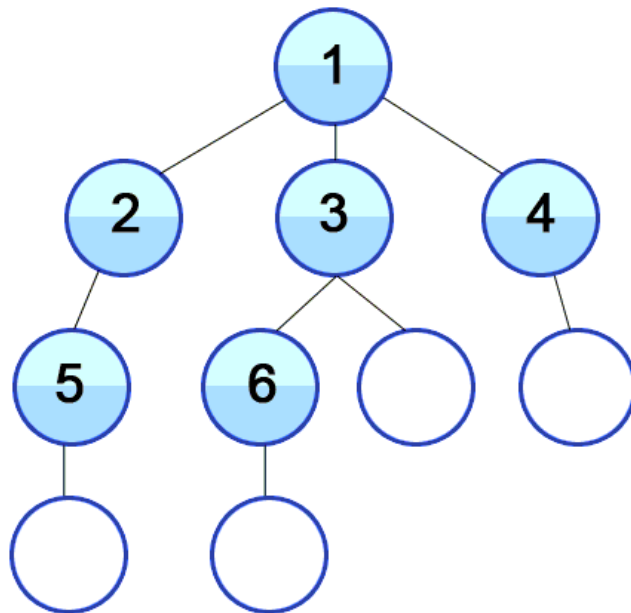
Compare and Swap

- Conventiionell
 - ReadCacheline(PTR) 64B Data
 - CAS(PTR,CompVal,New)
 - WriteCacheline(PTR) 64B Data
- Atomic CAS
 - Request_CAS(PTR, CompVal, New) 16B Data
 - Response 16B Data

- Problematic Workload
 - Low Computation Intensity
 - Low Locality
- Expectation
 - Efficient Bandwidth Usage

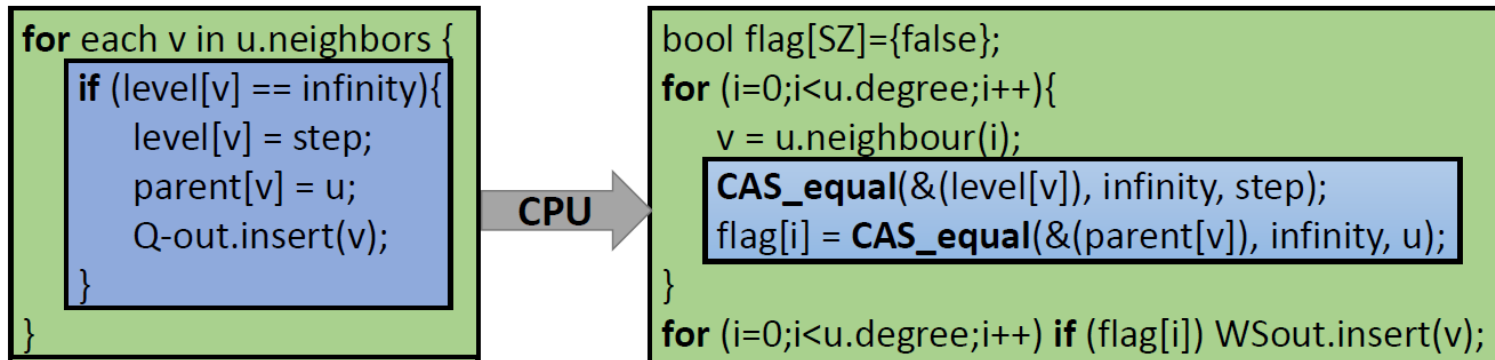
Example Workload: Graph Computing

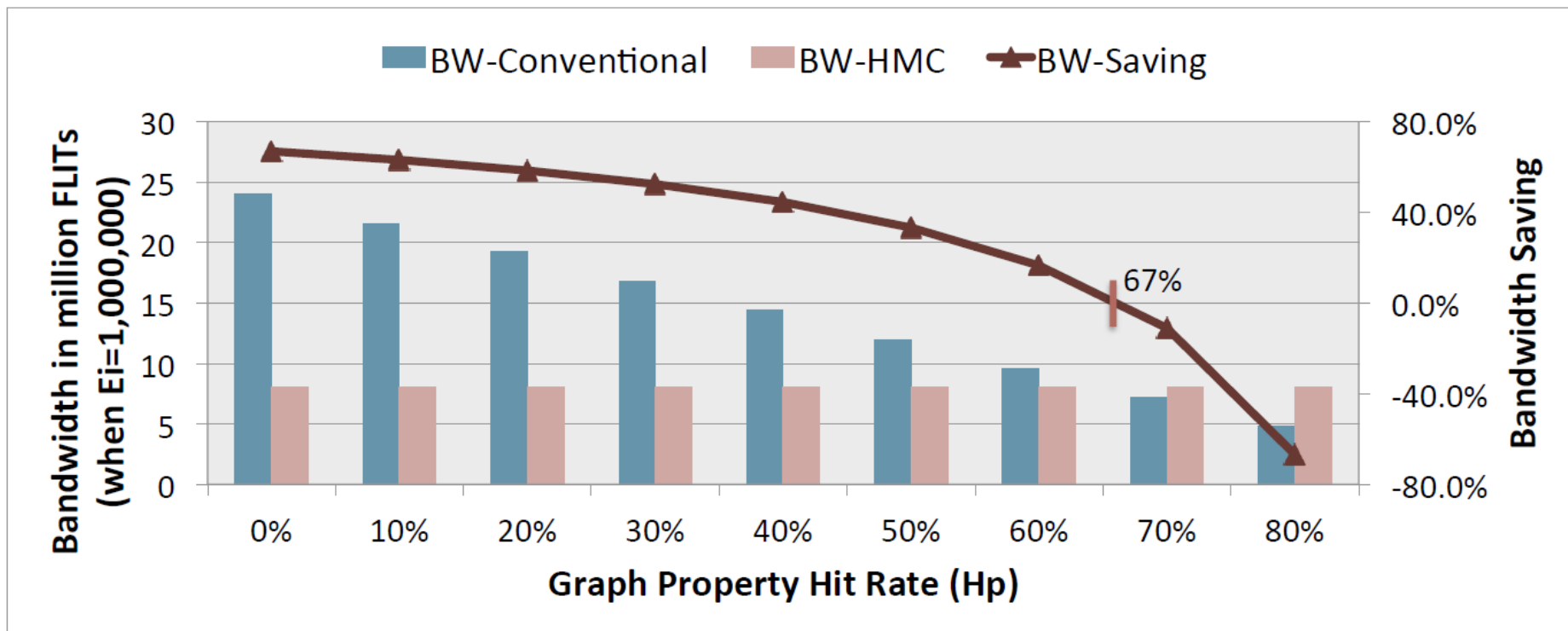
Graph Search



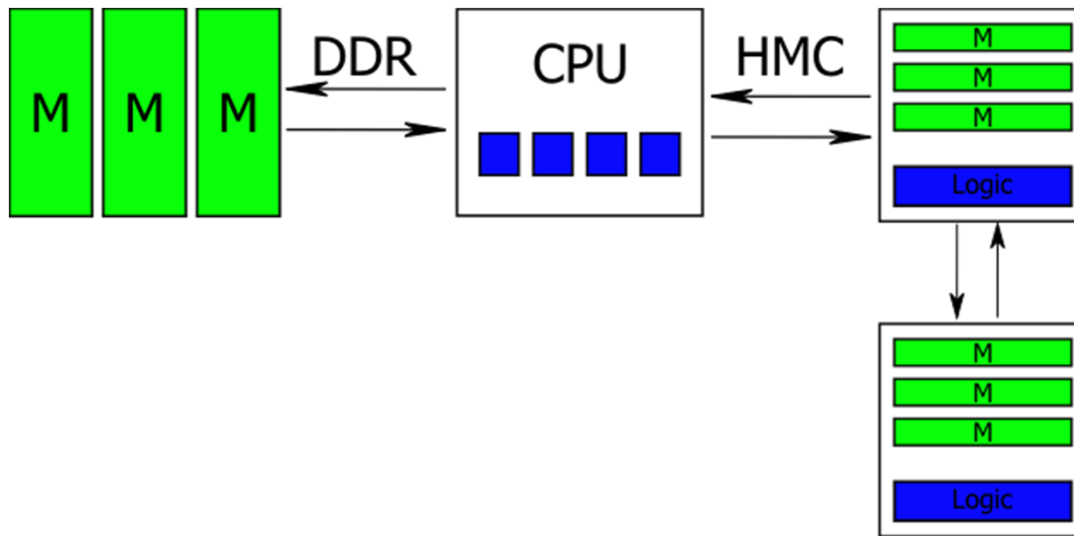
- Breadth-first Search
 - Check all Neighbors
 - Move to the next level

Processing in Memory Offloading



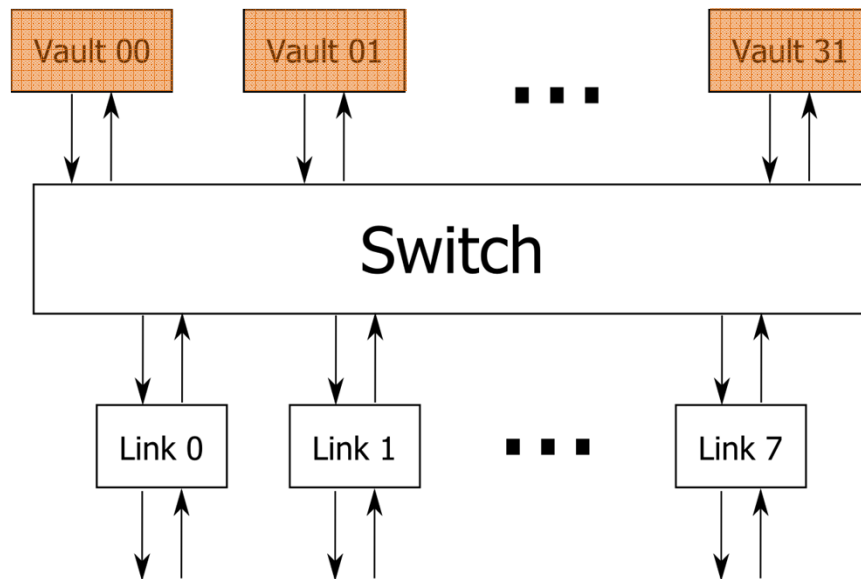


Processing in Memory Application Offloading – Tesseract



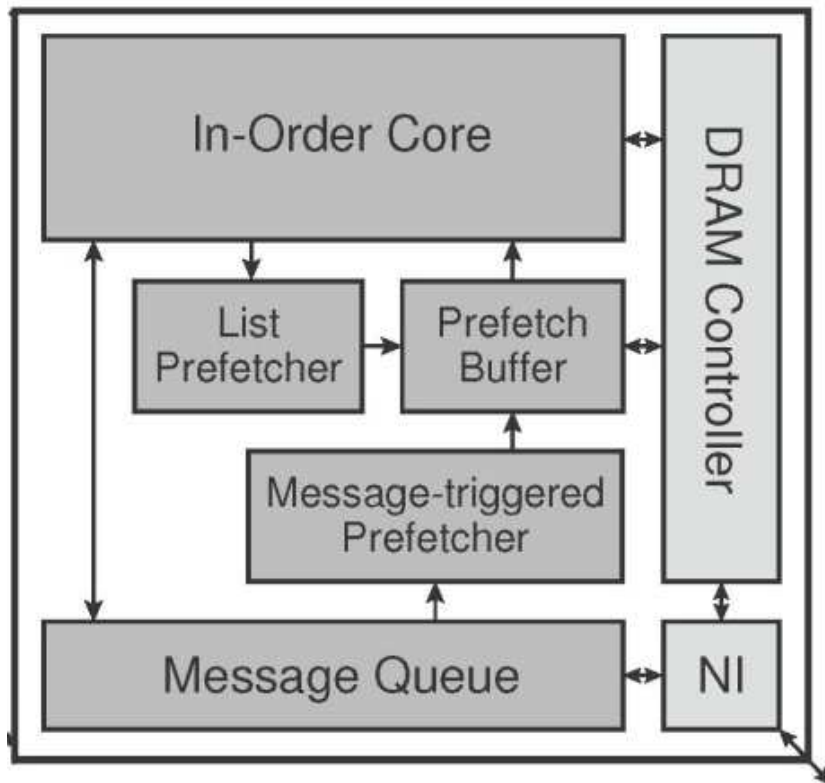
- Problematic Workload
 - Low Computation Intensity
 - Low Locality
- Expectation
 - Efficient Bandwidth Usage
 - High Energy Efficiency
 - Scalability

Processing in Memory Tesseract



- Single HMC
 - Max Interconnect Bandwidth: 160 GB/s
 - Max Memory Bandwidth: 256 GB/s
- Tesseract
 - PU in every Vault
 - 16 HMC in Network
 - Max Interconnect Bandwidth: 160 GB/s
 - Max Memory Bandwidth: 4 TB/s

Processing in Memory Tesseract Core Architecture



- Distributed Memory Architecture
 - No Cache Coherence
 - Remote Function Call
- List Prefetcher
 - Prefetch Stride (Cache Lines)
- Message Triggered Prefetcher
 - Preload Data before Message handling

Processing in Memory Tesseract – Speedup

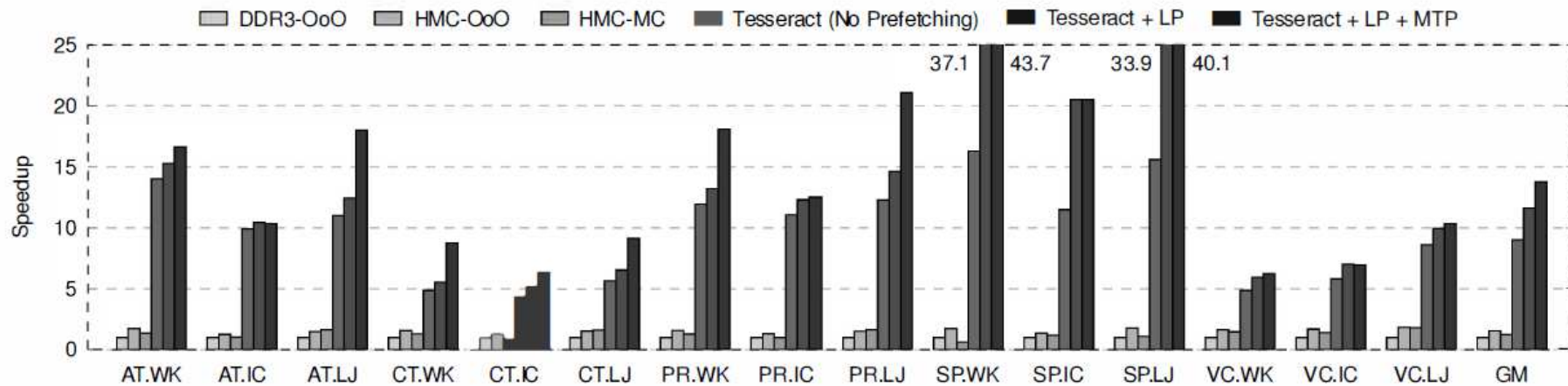
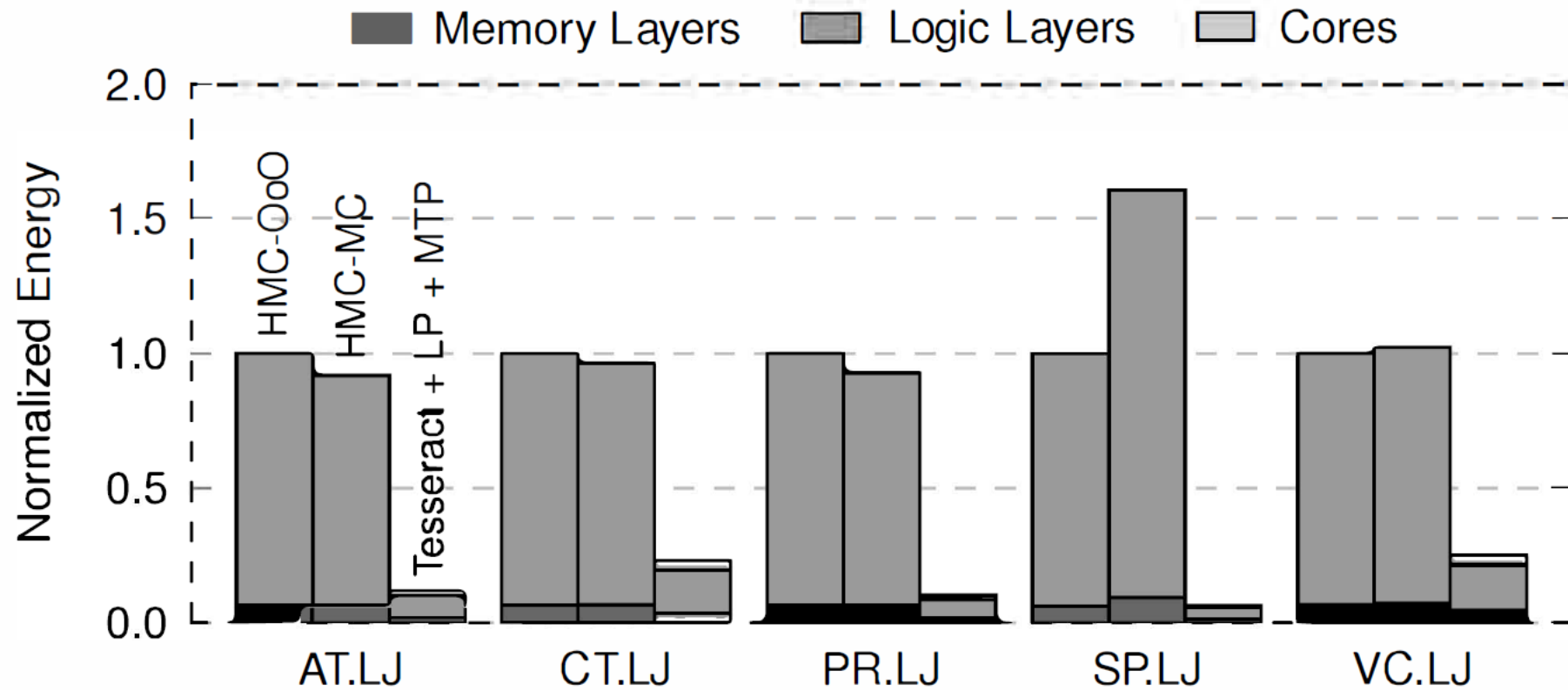


Figure 6: Performance comparison between conventional architectures and Tesseract (normalized to DDR3-OoO).

- HMC-OoO Architecture
 - 32 Performance Cores
 - 16 HMCs
 - 320GB/s Memory Bandwidth
- HMC-MC Architecture
 - 512 low-power Cores
 - 16 HMCs
 - 320GB/s Memory Bandwidth
- Tesseract
 - 512 low-power Cores
 - 16 HMCs
 - 4TB/s Memory Bandwidth

Processing in Memory Tesseract – Energy Efficiency



Processing in Memory Tesseract – Scalability

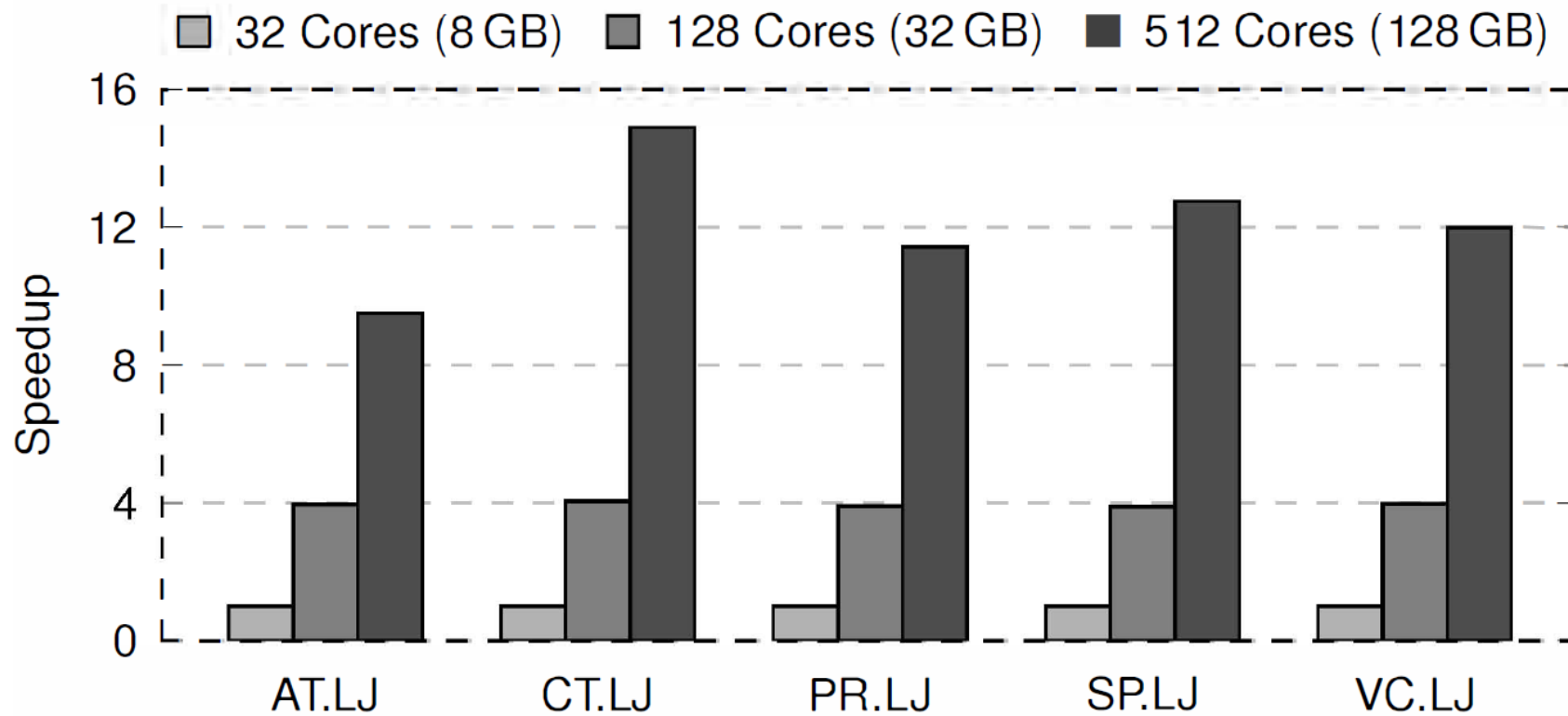


Figure 11: Performance scalability of Tesseract.

Conclusion Processing in Memory



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- High Speedup
- Highly Energy Efficient
- Scales proportional to Memory Capacity
- Currently usable via Instruction Offloading

- Current Designs optimized for Graph Computing

Future Work



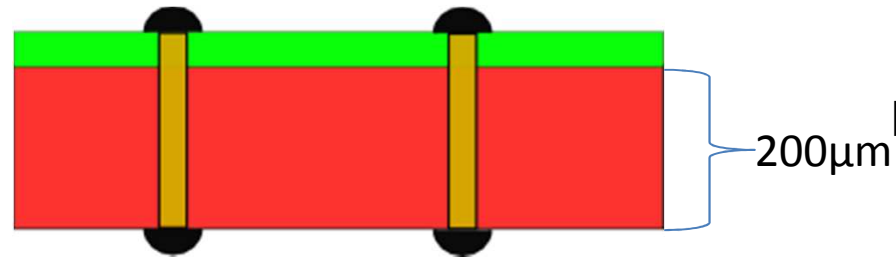
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- Additional Workloads
- Processing Units
 - Internode Communication
 - Application specific
 - General Purpose
 - FPGA technology?

Further Information

[MEMSYS International Symposium on Memory Systems](#)

Through – Silicon Via



μBumps on top Metal Layer

~ 50 μm pitch

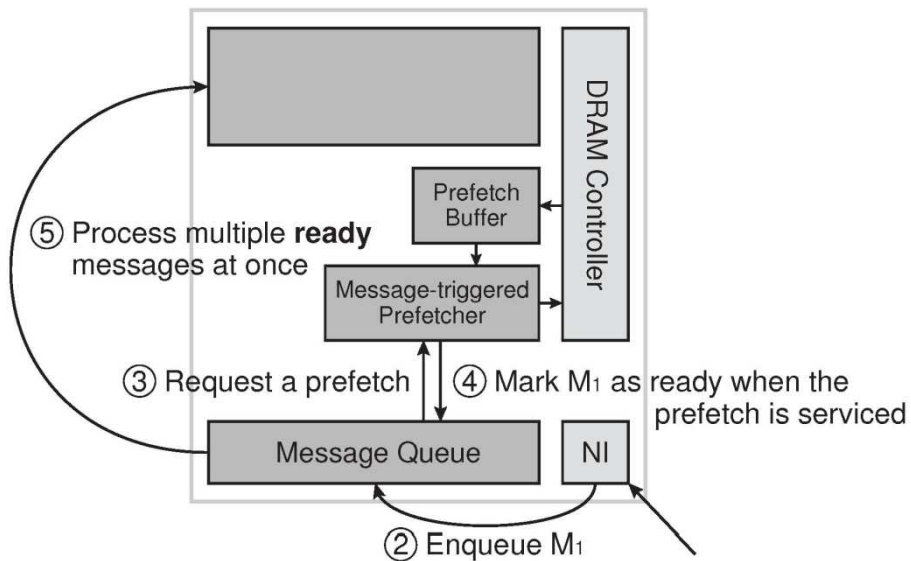
Through – Metal Via

~ 2 - 50 μm

μBumps under Substrate

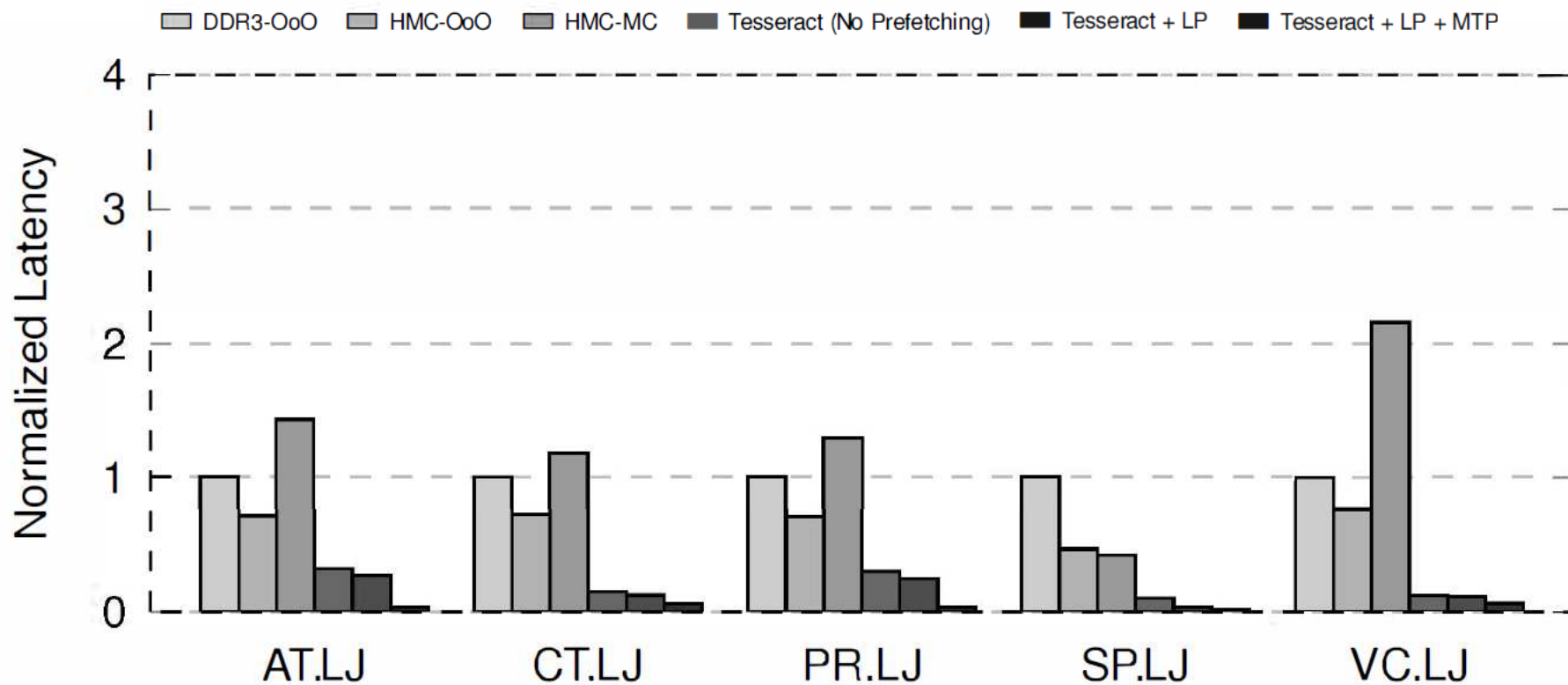
~ 50 μm pitch

Processing in Memory Tesseract Core Architecture



- Distributed Memory Architecture
 - No Coherence Traffic
 - Message / Instruction Passing
- Optional List Prefetcher
 - Optimize Locality
- Message Triggered Prefetcher
 - Preload Data before Message handling

Processing in Memory Tesseract – Latency



(b) Average memory access latency (normalized to DDR3-OoO)